

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Chun Hung LIN

New Divisional Application of S.N. 09/516,024

Filed:

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: Prior Group Art Unit: 2823  
:  
: Prior Examiner: D. Collins  
:

For: LOW-PIN-COUNT CHIP PACKAGE AND MANUFACTURING METHOD  
THEREOF

**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner for Patents  
Washington, D. C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

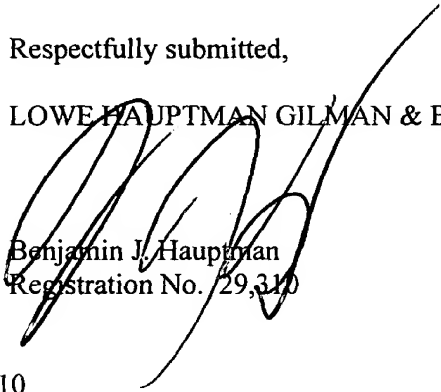
This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

New Divisional Application of S.N. 09/516,024

The references were cited by or submitted to the U.S. Patent and Trademark Office in parent application Serial No. 09/516,024, filed February 29, 2000, which is relied upon for an earlier filing date under 35 USC 120. Thus, copies of these references are not attached. 37 CFR 1.98(d).

Respectfully submitted,

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